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(12) **United States Design Patent**
Aoki et al.

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(54) **SEMICONDUCTOR DRIVING CIRCUIT
MODULE**

(71) Applicant: **TAMURA CORPORATION**, Tokyo
(JP)

(72) Inventors: **Hirotooshi Aoki**, Saitama (JP);
Kiyotaka Yoshida, Saitama (JP);
Tomohiko Yoshino, Saitama (JP)

(73) Assignee: **TAMURA CORPORATION**, Tokyo
(JP)

(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/162**

(58) **Field of Classification Search**
USPC D13/182, 133, 146, 110, 115, 173;
D14/217, 432, 433; D10/80, 103
CPC . H01L 21/00; H01L 21/4814; H01L 21/4846;
H01L 21/4871; H01L 21/67144; H01L
2224/42; H01L 2224/08054; H01L 23/12;
H01L 23/13; H01L 23/14; H01L 23/147;
H01L 23/58; H01L 2924/171; H01L
2924/1711; H01L 2924/1715; H01L
2924/17151; H01L 2924/1811; H01L
2924/1815; H01L 2924/19042; H01L
2924/1905; H01L 2924/181; H05B 41/14;
G02B 6/4256; G02B 6/4257; G02B
6/4261; G02B 6/4262; G02B 6/428;
G02B 6/4281;

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Primary Examiner — Vy N Koenig

Assistant Examiner — Seth David Kumpf

(74) *Attorney, Agent, or Firm* — JCIPRNET

(57) **CLAIM**

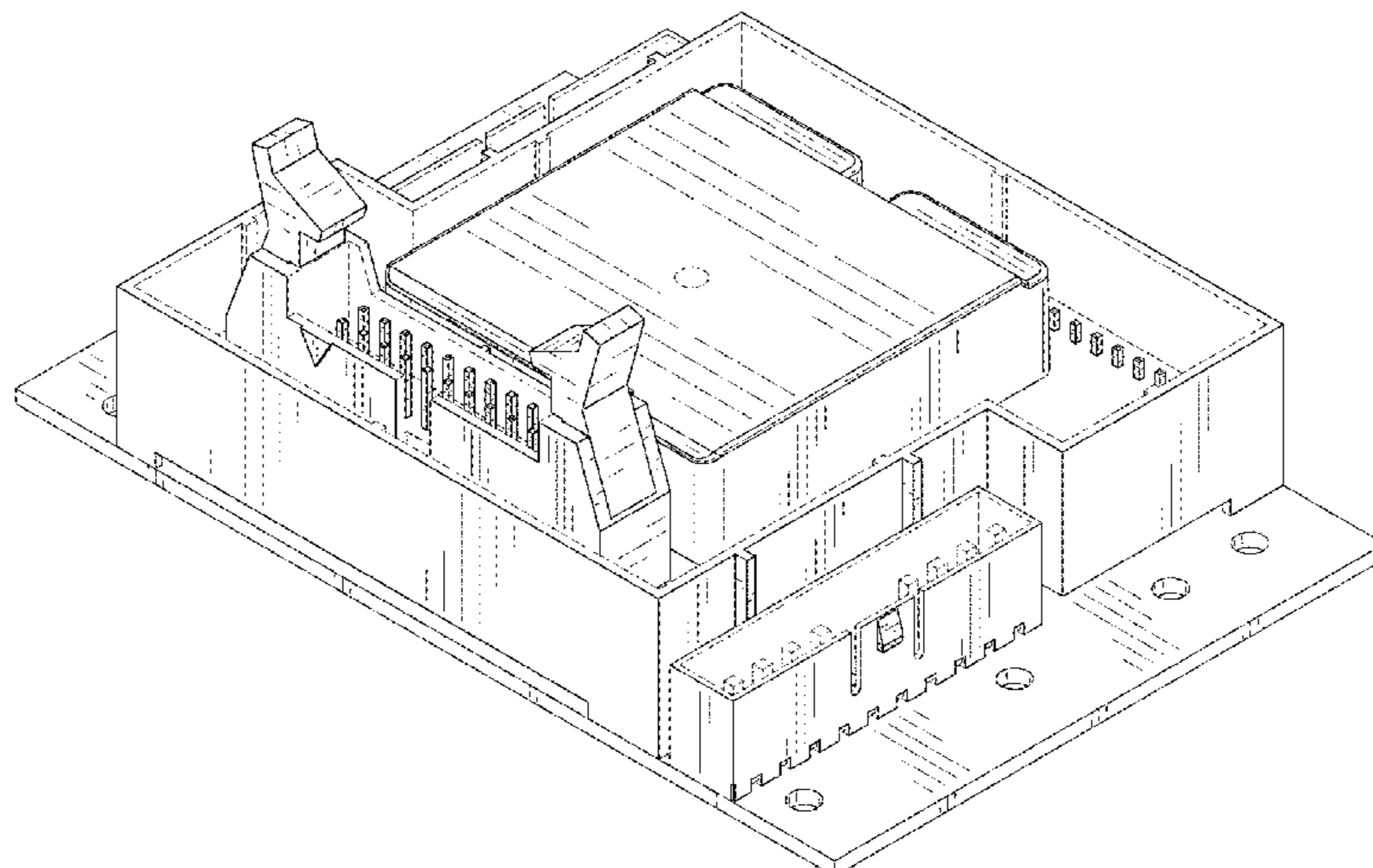
The ornamental design for a semiconductor driving circuit module, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a semiconductor driving circuit module showing our new design;
FIG. 2 is a front view of the semiconductor driving circuit module of FIG. 1;
FIG. 3 is a rear view of the semiconductor driving circuit module of FIG. 1;
FIG. 4 is a left side view of the semiconductor driving circuit module of FIG. 1;
FIG. 5 is a right side view of the semiconductor driving circuit module of FIG. 1;
FIG. 6 is a top view of the semiconductor driving circuit module of FIG. 1;
FIG. 7 is a bottom view of the semiconductor driving circuit module of FIG. 1; and,
FIG. 8 is a perspective view of the semiconductor driving circuit module of FIG. 1 mounted on a semiconductor element.

The broken lines shown in FIGS. 1-8 illustrate portions of the semiconductor driving circuit module that form no part of the claimed design. The broken lines showing the semi-

(Continued)



conductor element in FIG. 8 are for the purpose of illustrating environmental structure and form no part of the claimed design.

1 Claim, 5 Drawing Sheets

(58) **Field of Classification Search**

CPC H05K 1/14; H05K 1/141; H05K 1/142;
H05K 1/144; H05K 1/18; H05K 1/182;
H05K 1/026; H05K 1/181

See application file for complete search history.

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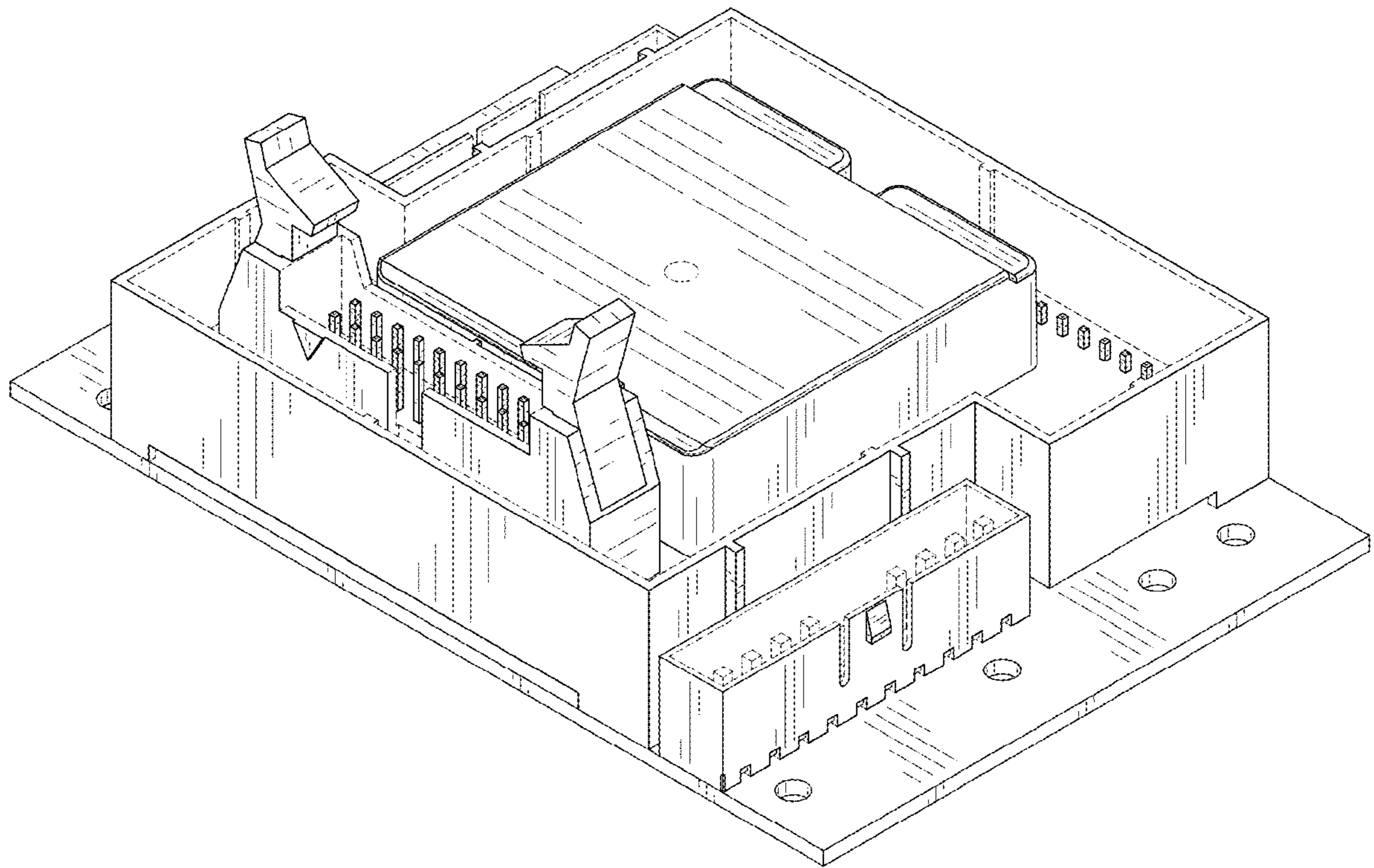


FIG. 1

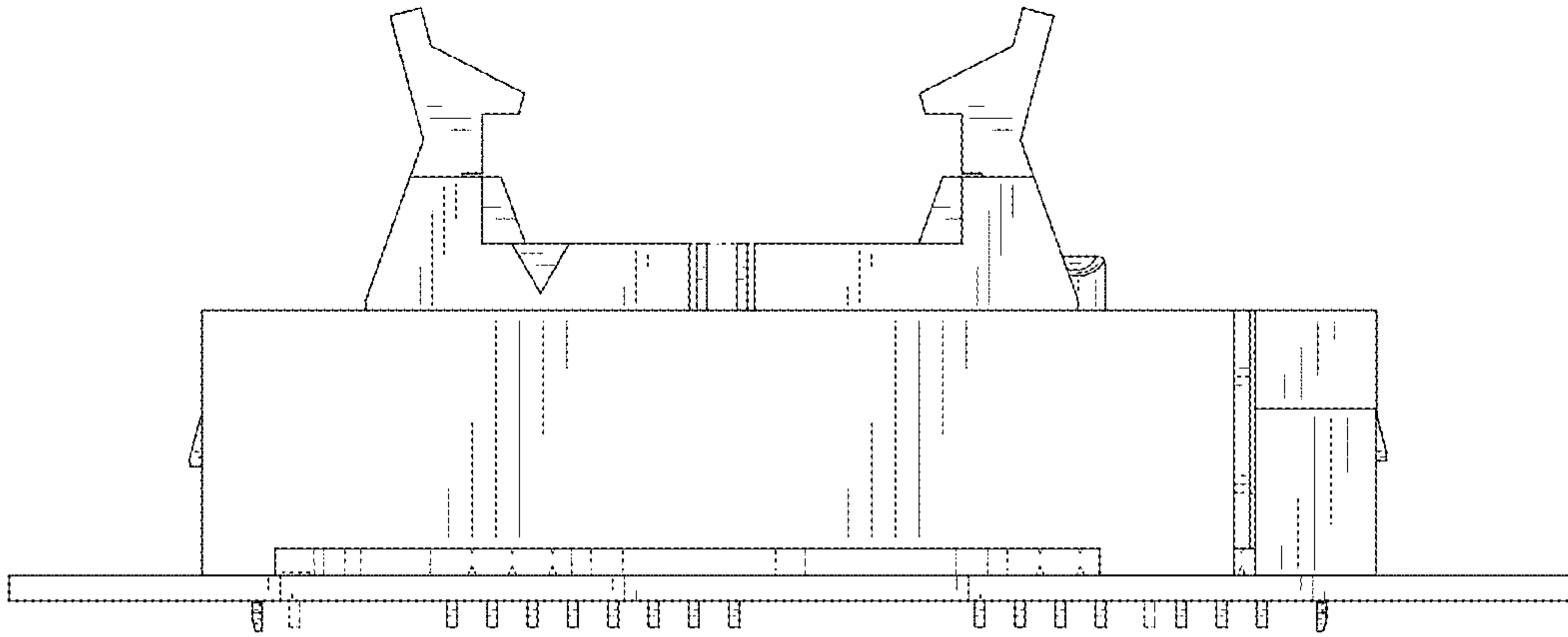


FIG. 2

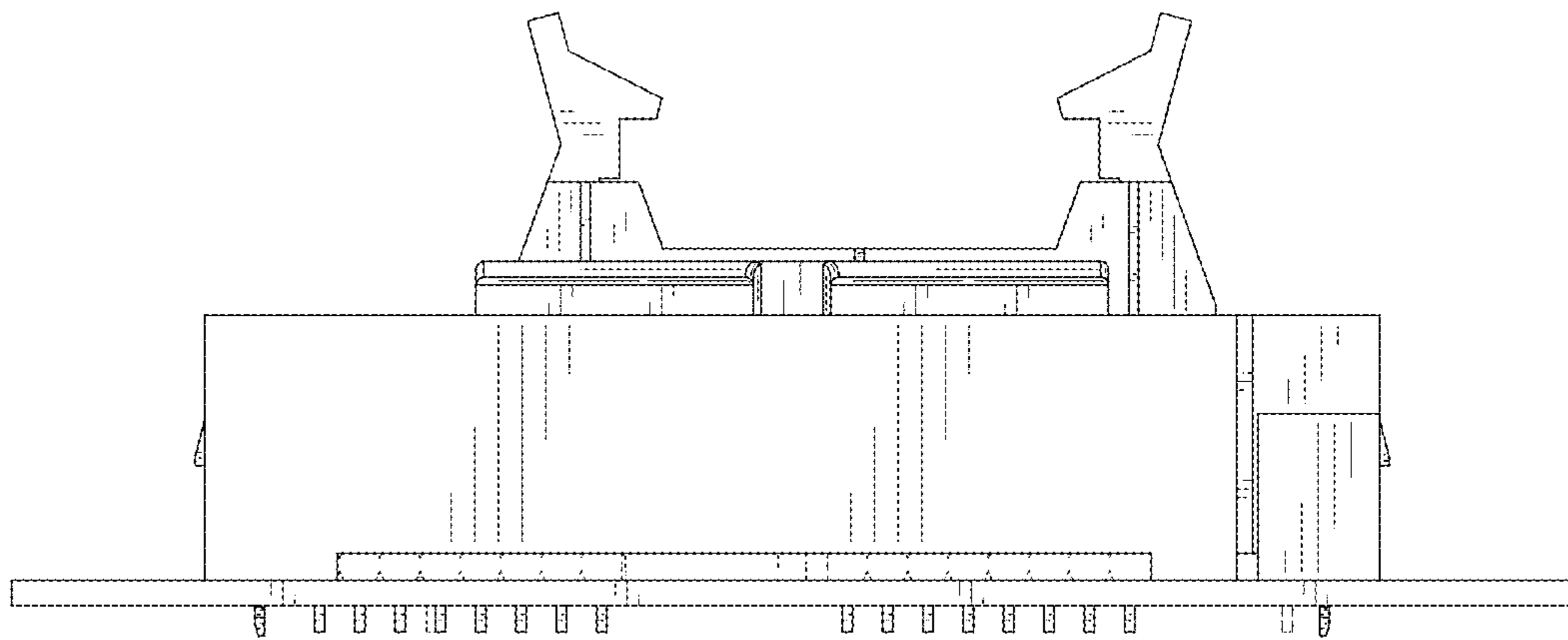


FIG. 3

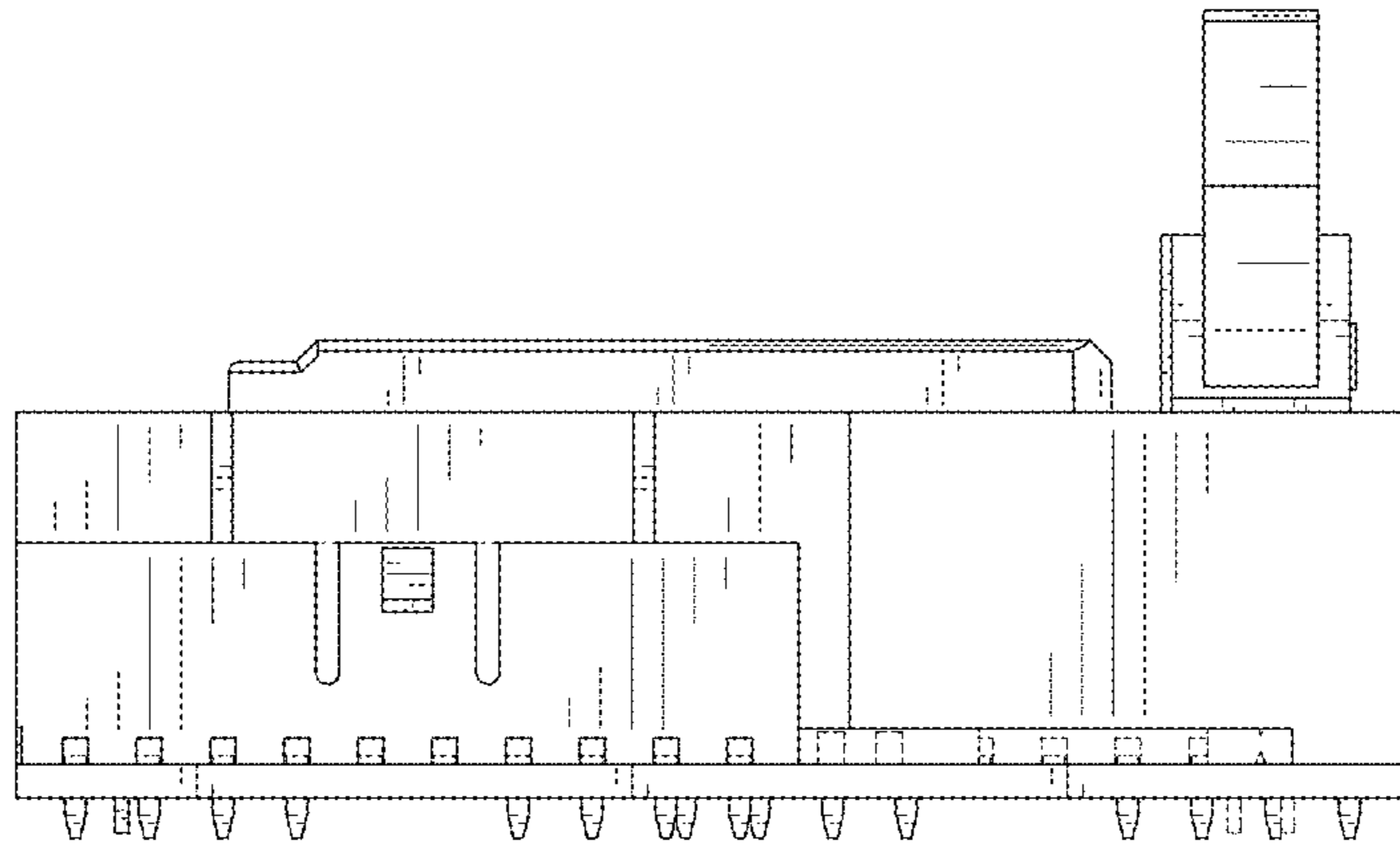


FIG. 4

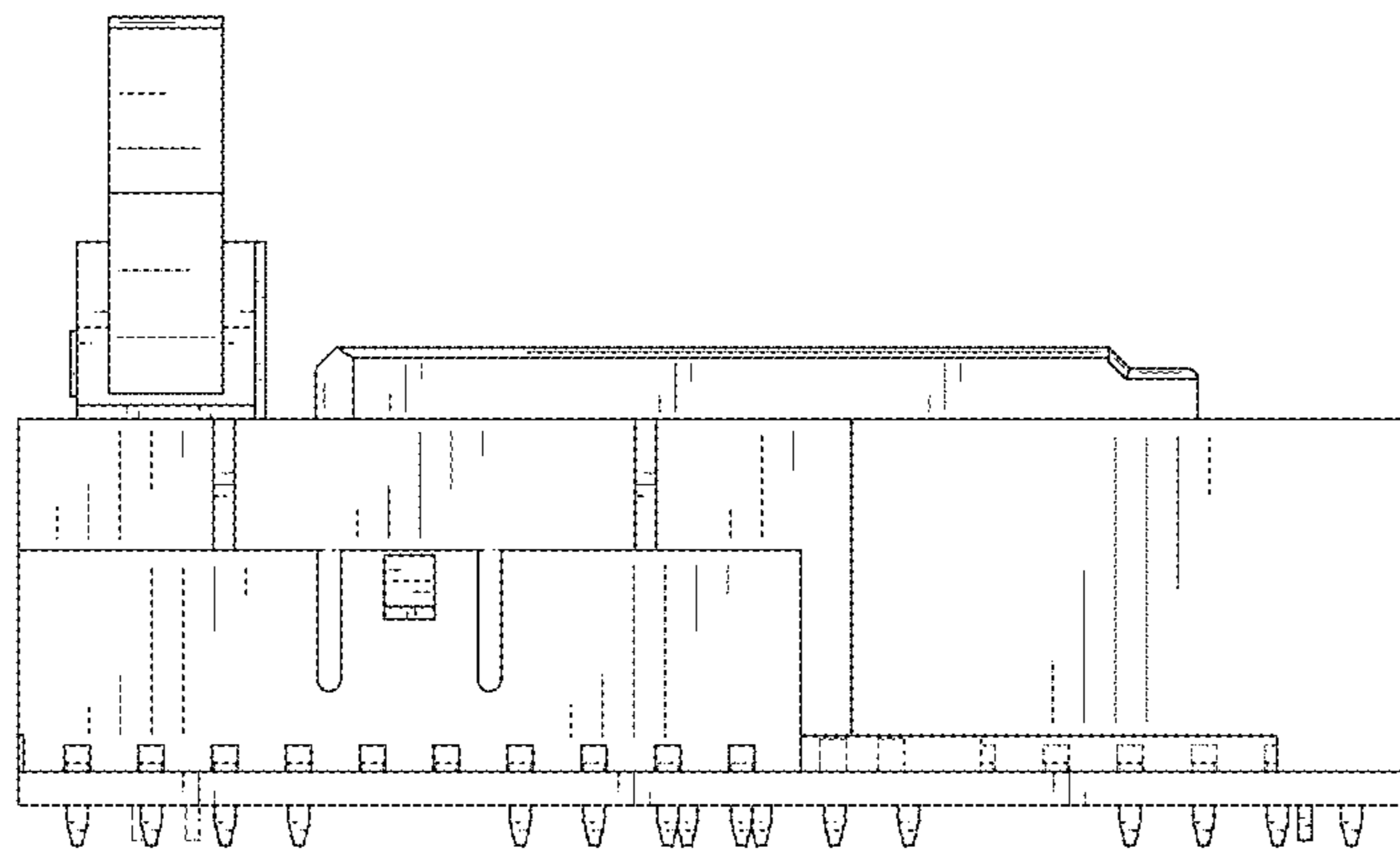


FIG. 5

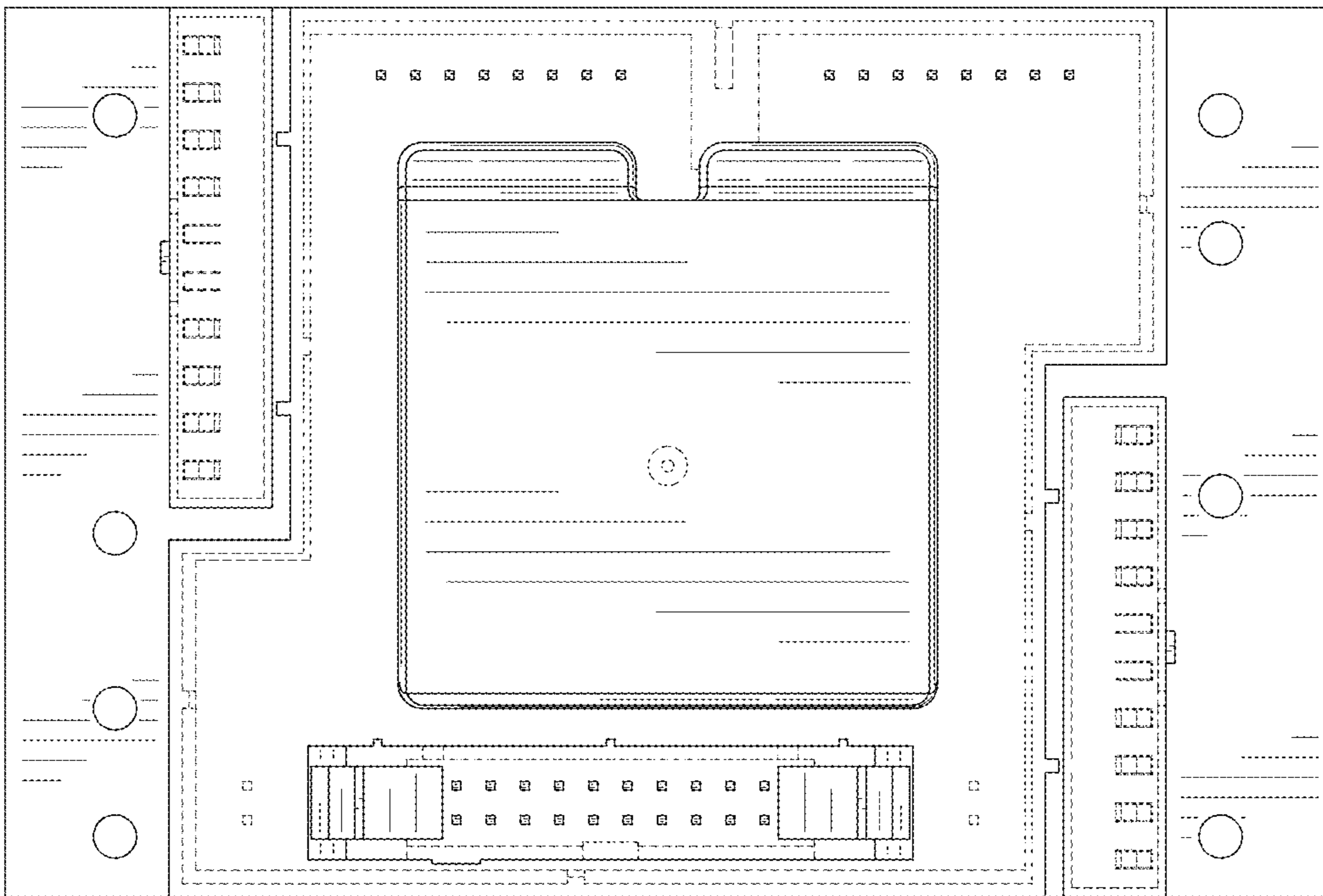


FIG. 6

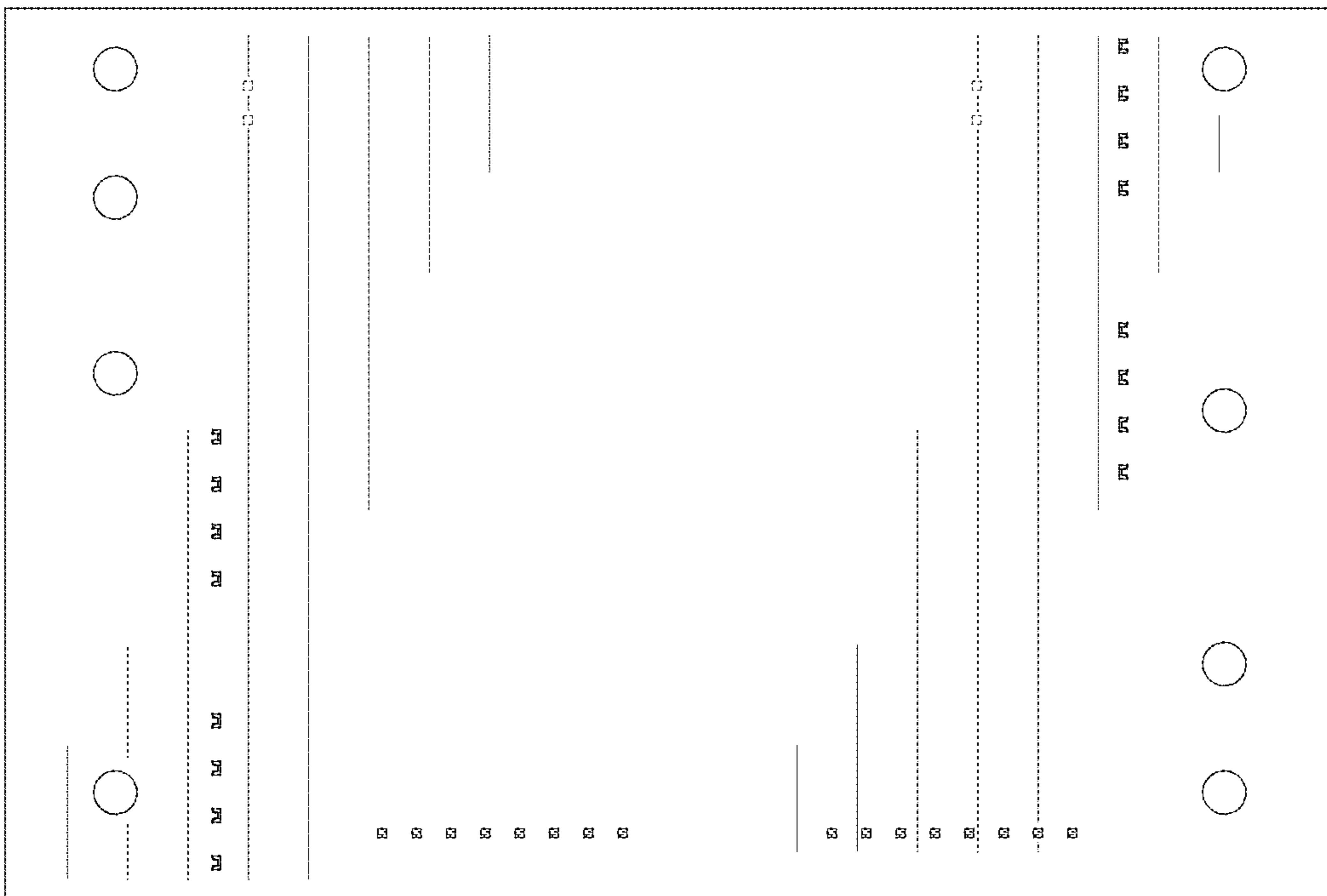


FIG. 7

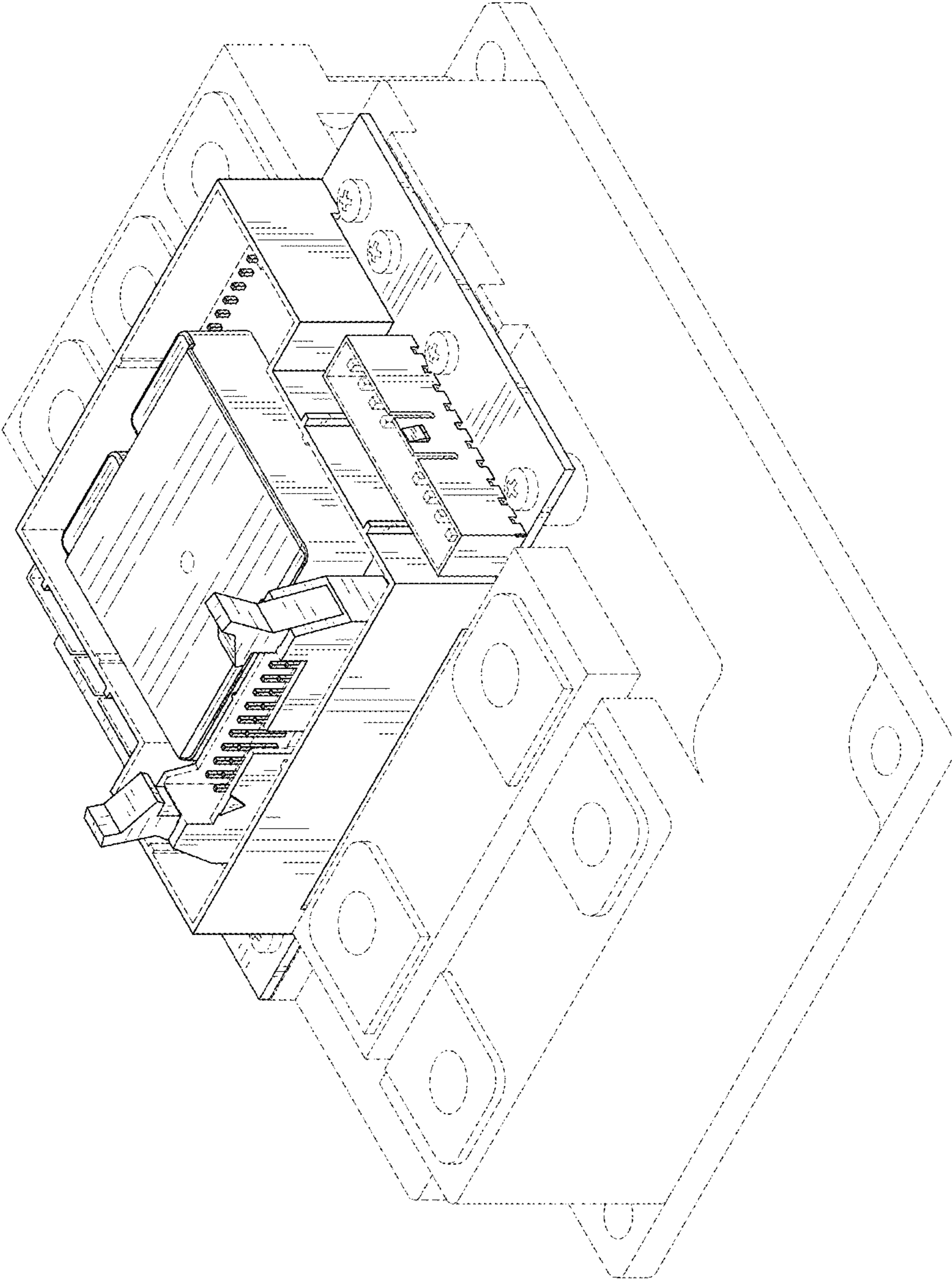


FIG. 8